

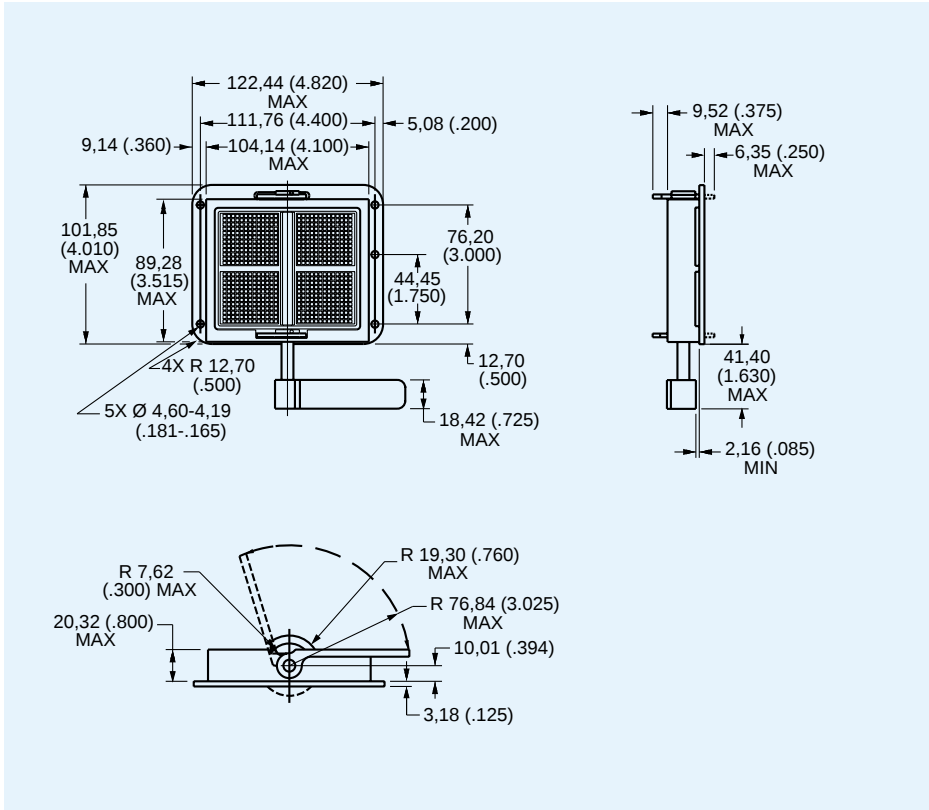
DL4 — Metal Frame — 624 Pin Connector — Crimp Contacts

Plug



- For contact cavity arrangement, see page 69.
- For panel cutout and mounting hole pattern, see page 65.
- Crimp contacts are to be ordered separately and installed by customer, see pages 52-53.
- Actuating handle is part of completed assembly.

Part Number	Nomenclature
110959-0002	DL4-624P

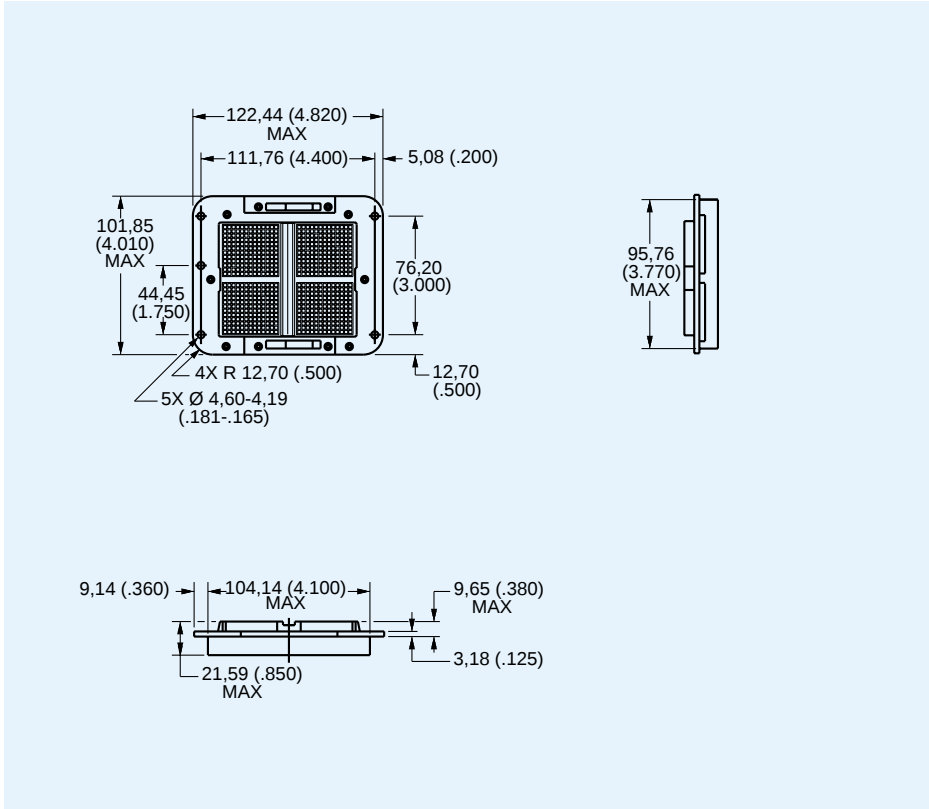


Receptacle



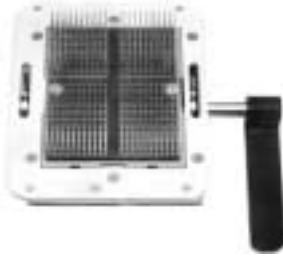
- For contact cavity arrangement, see page 69.
- For panel cutout and mounting hole pattern, see page 65.
- Crimp contacts are to be ordered separately and installed by customer, see pages 52-53.

Part Number	Nomenclature
110960-0002	DL4-624R

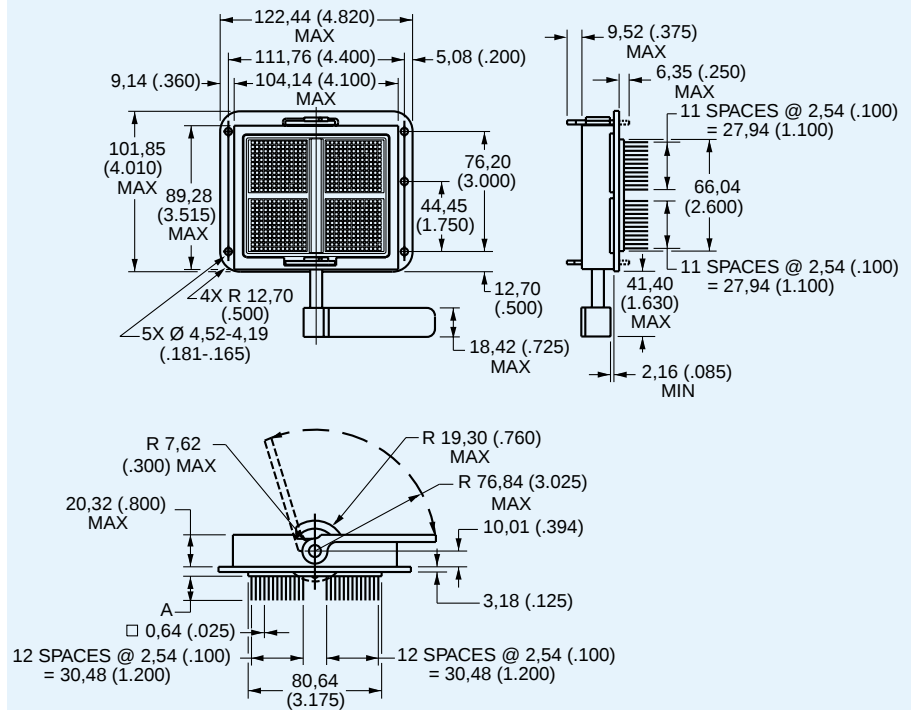


DL4 — Metal Frame — 624 Pin Connector — Square Post Contacts

Plug



- For contact cavity arrangement, see page 69.
- For panel cutout and mounting hole pattern, see page 65.
- Front Removable 0,64 (.025) Square Posts 2,54 (.100) Centers.
- Actuating handle is part of completed assembly.

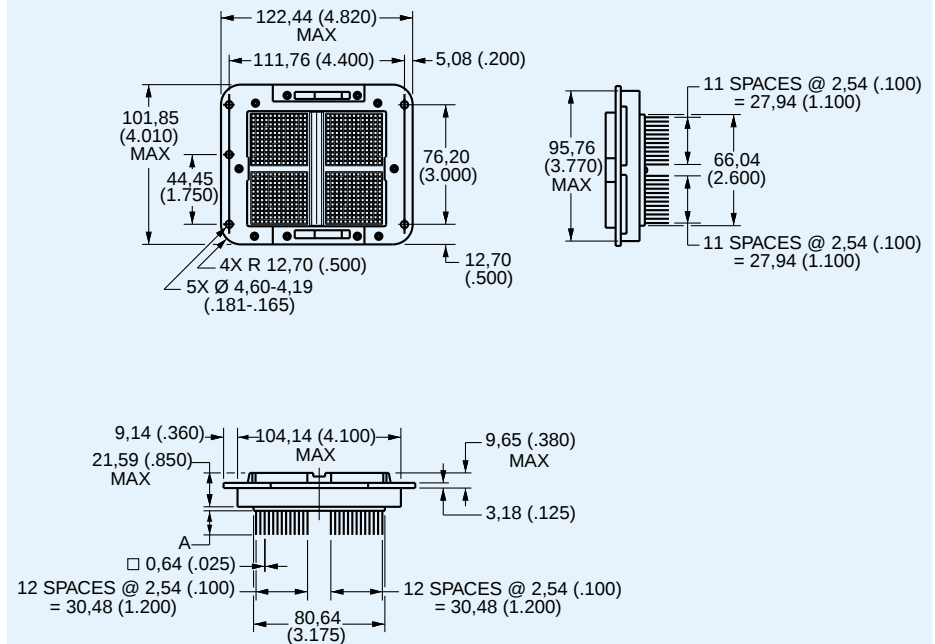


Part Number	Nomenclature	A
110959-0011	DL4-624PW4	15,37 (.605)
110959-0035	DL4-624PW4A	15,37 (.605)
110959-0042	DL4-624PW6A	7,11 (.280)

Receptacle



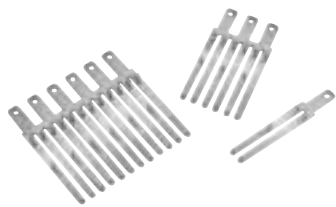
- For contact cavity arrangement, see page 69.
- For panel cutout and mounting hole pattern, see page 65.
- Front Removable 0,64 (.025) Square Posts 2,54 (.100) Centers.



Part Number	Nomenclature	A
110960-0022	DL4-624RW4	15,37 (.605)
110960-0045	DL4-624RW4B	15,37 (.605)
110960-0048	DL4-624RW6B	7,11 (.280)

Buss Contacts

6 Pair/3Pair/1 Pair

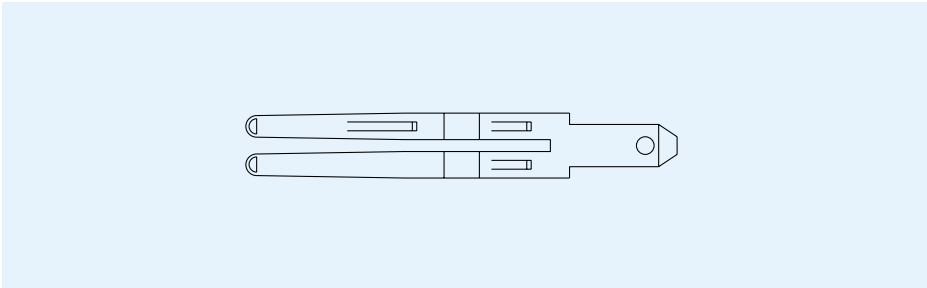


- Designed for power distribution of more than 5 amps.
- Accommodates #30-#18 AWG in hole Ø 1,29-1,14 (.051-.045) for wire soldering.
- Accommodates 1/8" crimp lugs for larger wire sizes.

Material: Copper Alloy

Finish: 20µ inch in mating area/
gold flash on balance (terminating end)

1 Pair

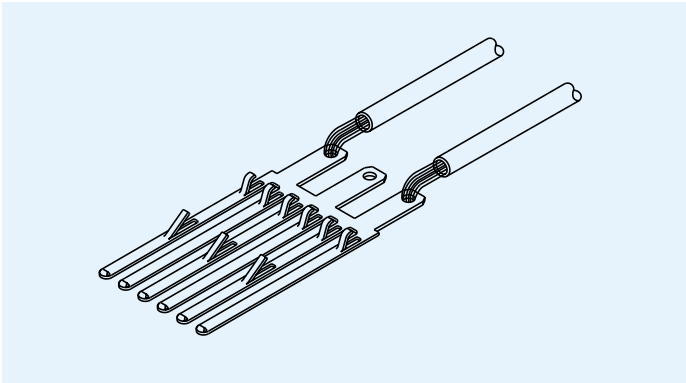


Buss Contact

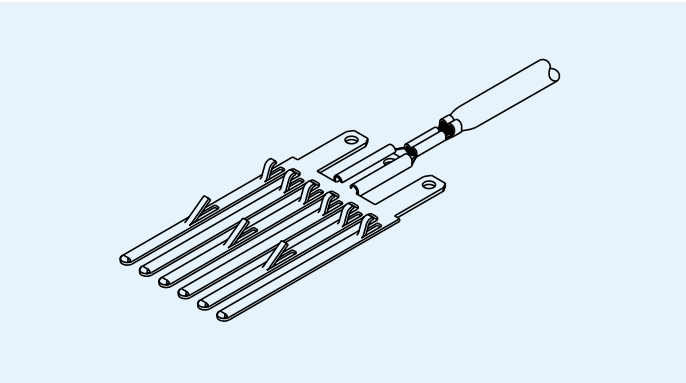
Description	Part Number
1 Pair	030-7380-001
2 Pair	030-7380-002
3 Pair	030-7380-003
4 Pair	030-7380-004
5 Pair	030-7380-005
6 Pair	030-7380-006

Note: For more information on tools and assembly, see pages 54-59.

Wire Termination — Solder



Wire Termination — Crimp Lug



Crimp Contacts — Loose

Loose

50µ inch gold contacts:

- Recommended for all applications.
- Offer the broadest amperage range.
- Mandatory for low current applications (less than 100 milliamps).

Material:	Copper Alloy
Finish:	Gold over nickel
Extraction Tool:	274-7029-007
Insertion Tool:	None Required

Plug (Bump)



Receptacle (Flat)

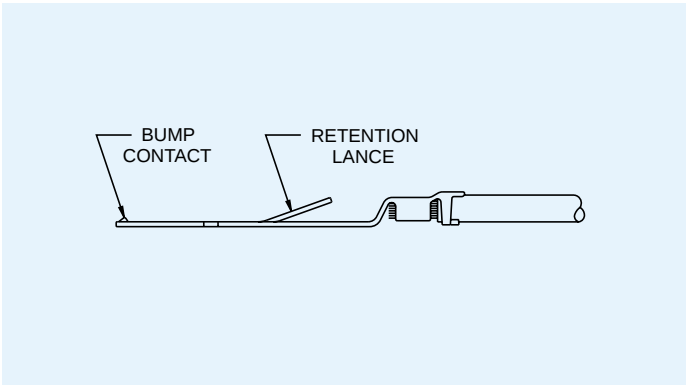


Wire Accommodation	Plug 50µInch Gold Bump●	Receptacle 50µInch Gold Flat●	Plug and Receptacle 20µInch Gold	Hand Tool (Page 55)
36 thru 38 AWG	—	—	127000-2207 + *	▲
28 thru 32 AWG	030-2416-003	030-2494-001	030-2416-001 ■	1
24 thru 26 AWG	030-2410-003	030-2492-001	030-2410-001 ■	2
20 thru 22 AWG	030-2409-003	030-2491-001	030-2409-001 ■	2
18 thru 20 AWG ♦	030-2415-003	030-2493-001	030-2415-001 ■	3

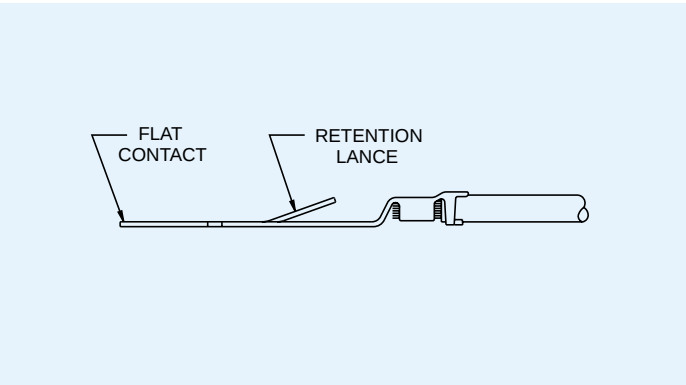
Note: For more information on tools and assembly, see pages 54-59.

- ♦ Non Insulation Support
- + Sold in lots of 100 pieces.
- For low current applications (less than 100 milliamps) use 50µ inch gold (bump) contact on plug side and 50µ inch flat gold (flat) contact on receptacle side.
- ▲ Contact Factory for tool.
- * Finish: 20µ inch gold in mating area/Gold flash on balance (terminating end).
- Finish: 20µ inch gold in mating area/Tin lead on balance (terminating end).

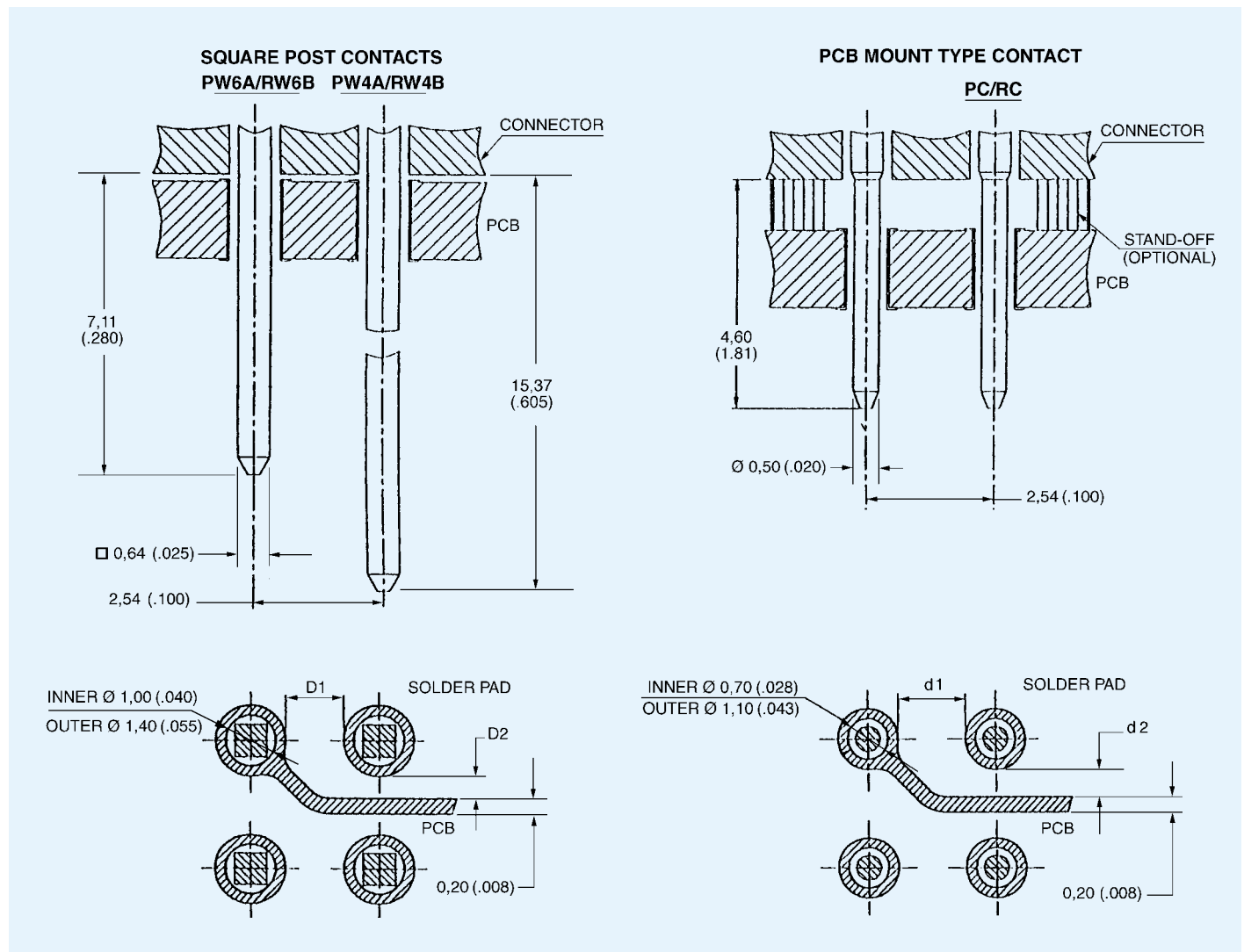
Plug (Bump)



Receptacle (Flat)



PCB Pad Layout



For the PC/RC Versions; The contact tail design has been modified from a 0,64 (.025) square pin to a 0,05 (.020) diameter round pin. The change enables a decrease in the diameter of the through-holes as well as the solder mounds on PCB's (d1,

and d2 can be wider than D1 and D2). This can reduce the crosstalk in RF circuits and enhance the dielectric withstanding voltage in high voltage circuits.

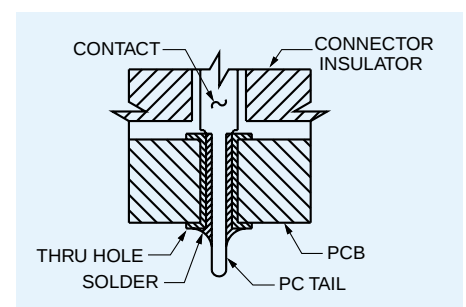
Dimensions	
D1	1,14 (.045)
D2	0,47 (.018)
d1	1,44 (.057)
d2	0,62 (.024)

PCB Pad Layout

The soldering of contacts into through (THRU) holes on a PC Board has become standard for medical equipment and test equipment for semi-conductors. As a result of the narrow spacing between the solder pad and circuit pattern, crosstalk between signals increases. A solution to this problem is to make the diameter of the contacts and solder lands smaller to provide more space between the lands and the patterns.

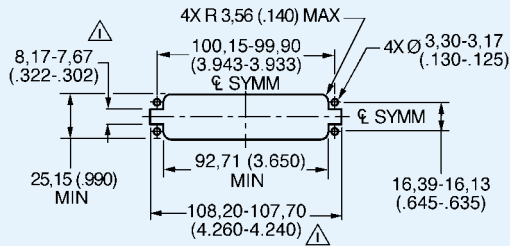
However, a smaller diameter contact results in higher impedance.

Cannon designed a solution with a smaller diameter contact tail. This design application allows the use of a smaller through-hole diameter.

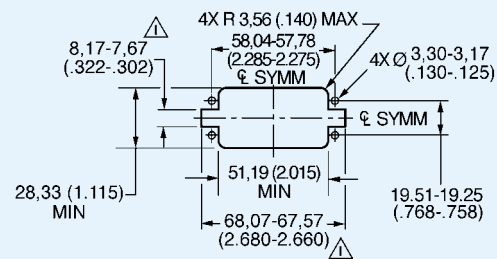


DL/DLM Panel Cutouts and Mounting Hole Patterns

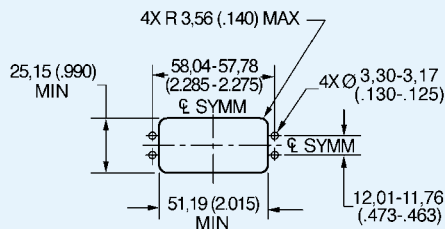
DL1-156/DLM1-156



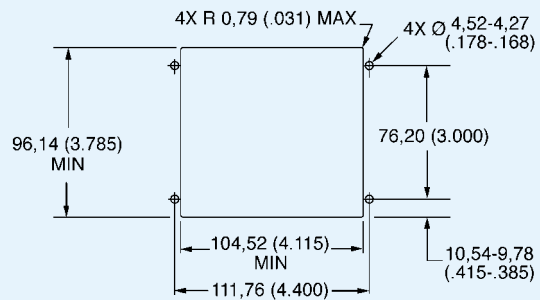
DL2-96/DLM2-96



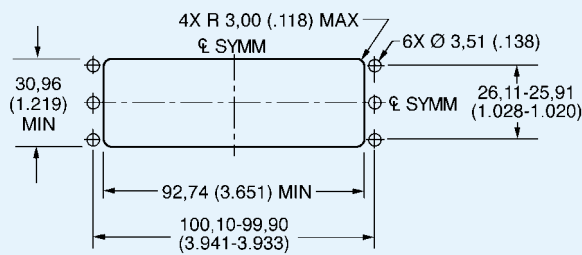
DL3-60/DLM3-60



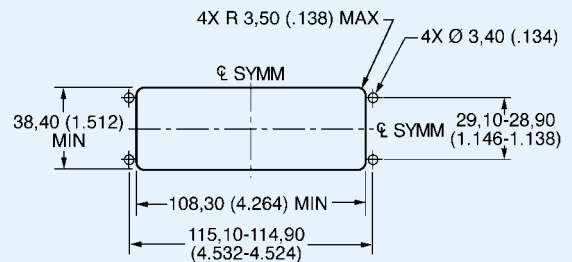
DL4-624



DL5-260/DLM5-260

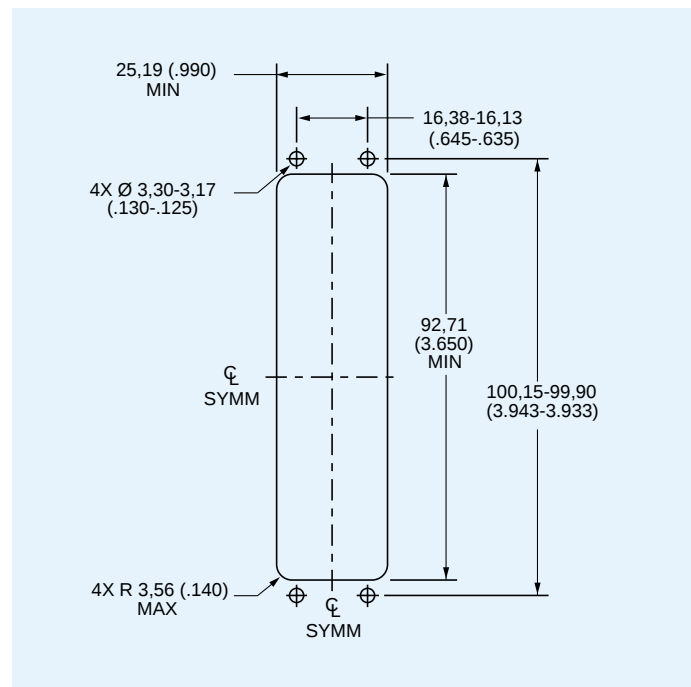


DLM6-360

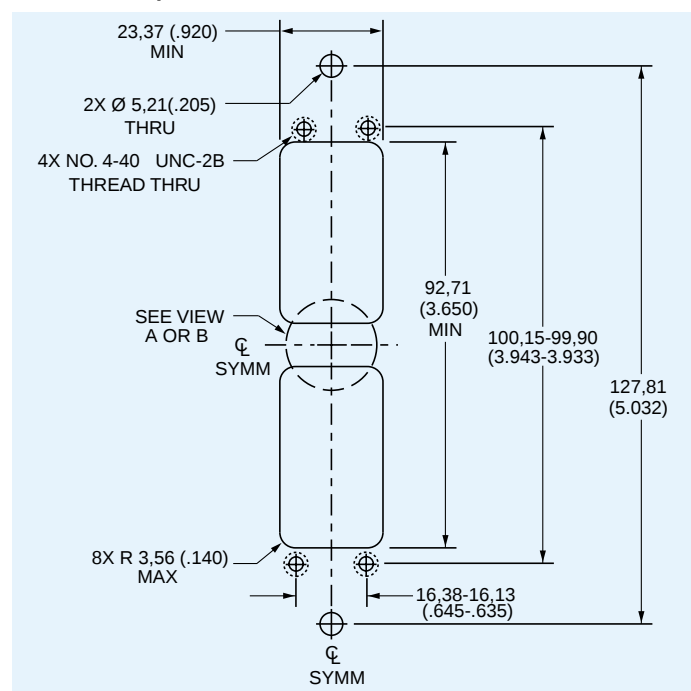


DLD1 Panel Cutouts and Mounting Hole Patterns

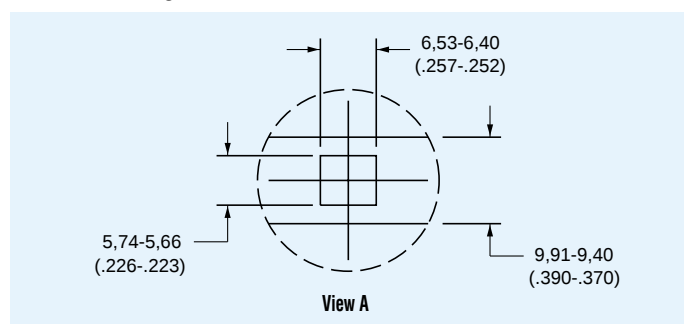
DLD1-156 Plug



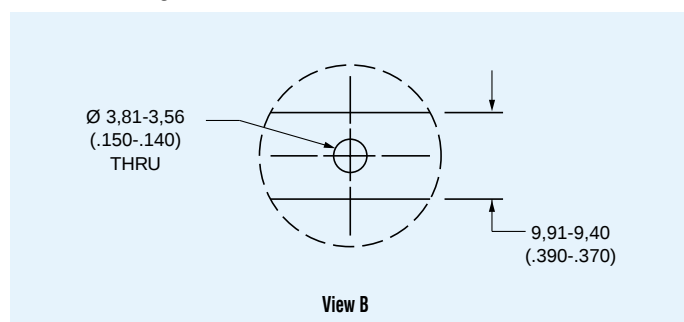
DLD1-156 Receptacle



Front Panel Bridge

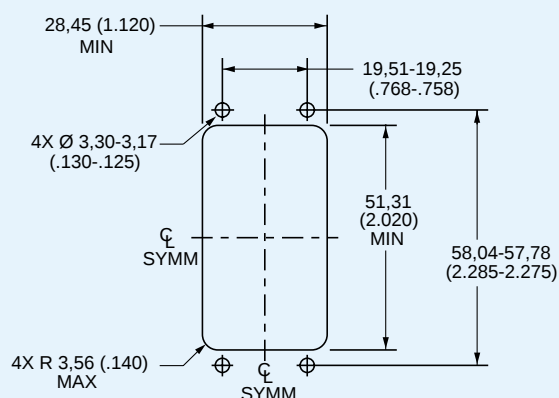


Rear Panel Bridge

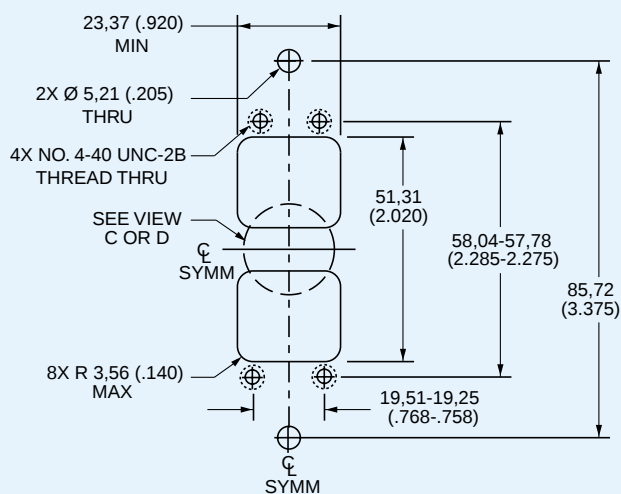


DLD2 Panel Cutouts and Mounting Hole Patterns

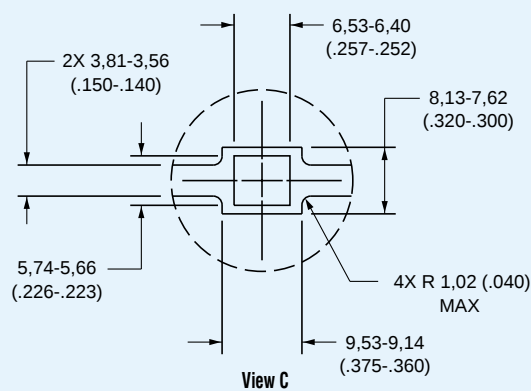
DLD2-96 Plug



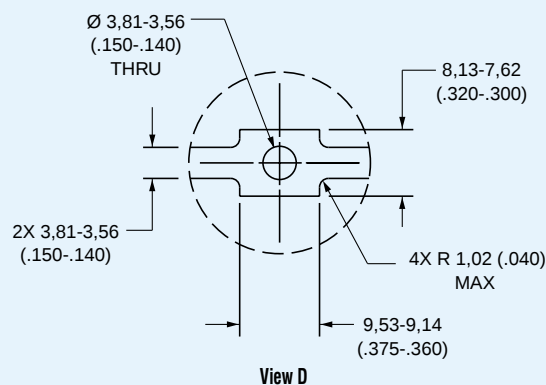
DLD2-96 Receptacle



Front Panel Bridge

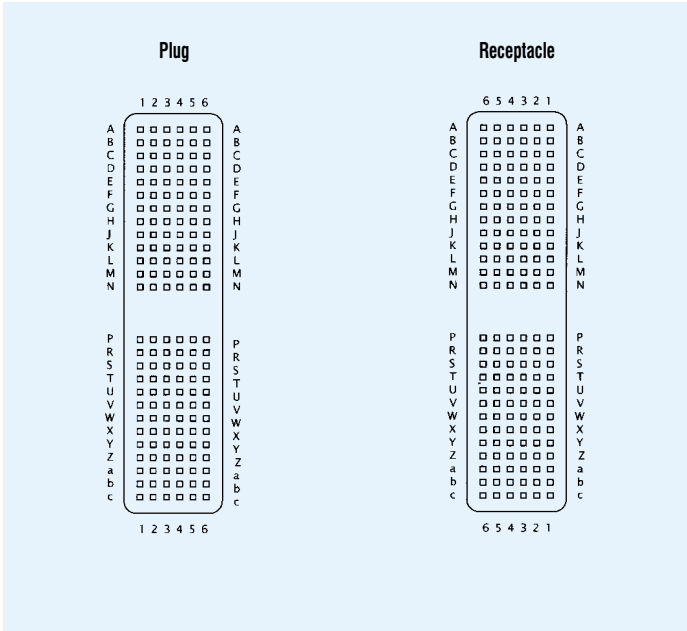


Rear Panel Bridge

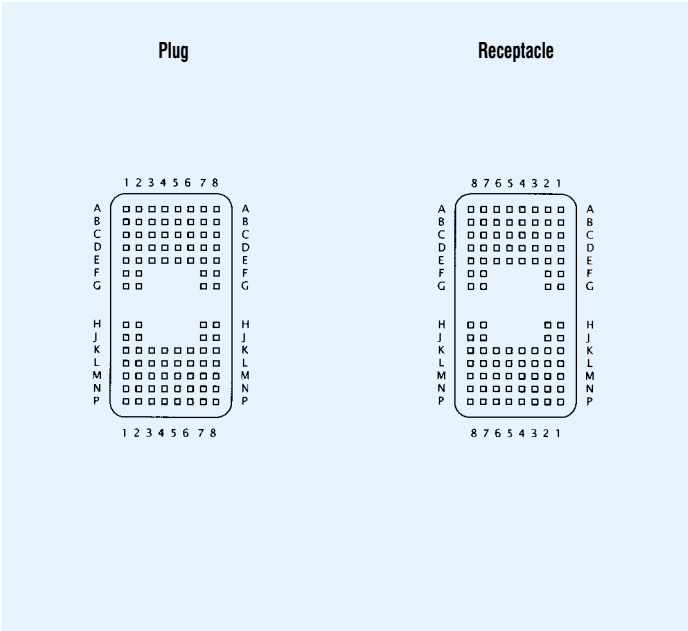


Contact Cavity Arrangements – Rear View

DL1-156/DLM1-156/DLD1-156



DL2-96/DLM2-96/DLD2-96



DL3-60/DLM3-60

